

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-14. (Canceled)

C1 15. (Currently Amended) A semiconductor device comprising:

a semiconductor chip;

a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate; and

resin for sealing the semiconductor chip;

wherein the semiconductor device has side surfaces, each of the side surfaces are flat, each of the side surfaces are made of at least an edge surface of the substrate and an edge surface of the resin, the edge surfaces of the substrate and the resin are level with each other, a pair of the side surfaces make a corner portion, and a hole is formed in the substrate such that the substrate is indented at the corner portion further inward than a portion of the resin.

16. (Previously Amended) The semiconductor device as defined in claim 15,

wherein the substrate at the corner portion forms a shape that is indented in the opposite direction from the direction in which the corner portion protrudes, and thus an indented surface of the substrate is positioned further inward than the portion of the resin.

17. (Canceled)

18. (Previously Amended) The semiconductor device as defined in claim 15,

wherein an indented surface of the substrate is covered by the resin.

19. (Previously Amended) The semiconductor device as defined in claim 15,

wherein a cover is provided at the corner portion, between the substrate and the resin; and

wherein an indented surface of the substrate is exposed.

20. (Original) A circuit board on which is mounted the semiconductor device as defined in claim 15.

21. (Original) Electronic equipment provided with the semiconductor device as defined in claim 15.

22-28. (Canceled)

CI
cont.
--29. (New) The semiconductor device as defined in claim 15, wherein the hole is a through-hole.--

--30. (New) The semiconductor device as defined in claim 15, wherein the hole is formed by a thinner portion in the substrate.--

--31. (New) A semiconductor device comprising:

a semiconductor chip;

a substrate on which the semiconductor chip is mounted and which is formed by cutting apart a larger substrate; and

resin for sealing the semiconductor chip;

wherein the semiconductor device has side surfaces, each of the side surfaces are flat, each of the side surfaces are made of at least an edge surface of the substrate and an edge surface of the resin, the edge surfaces of the substrate and the resin are level with each other, a pair of the side surfaces make a corner portion, and the substrate has a thinner portion at the corner portion.
